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COMPONENT

Title (de)
BAUELEMENT

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Application
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Abstract (en)
[origin: WO03094234A2] The invention relates to a component, particularly a semiconductor component, comprising a first chip (10), which is placed on a second chip (20). The main surfaces (13, 23) of the first and second chips (10, 20) are respectively provided with first and second metallizations (12, 22) that face one another. First areas of the metallizations (12, 22) are provided for establishing an electrical connection between the first and second chip (10, 20). According to the invention, second areas of the metallizations (12, 22) are provided in the form of an additional electrical functional layer located outside of the first and second chips (10, 20).

IPC 1-7
H01L 25/065; **H01L 23/528**; **H01L 23/544**

IPC 8 full level
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CPC (source: EP US)
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C-Set (source: EP US)
1. **H01L 2924/351 + H01L 2924/00**
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